



# Status of the SOI monolithic active pixel detector development

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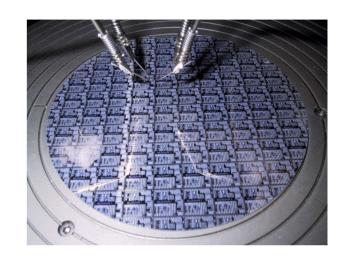
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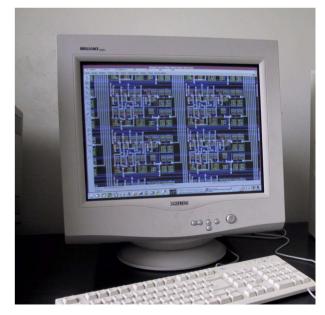


## **Outline**

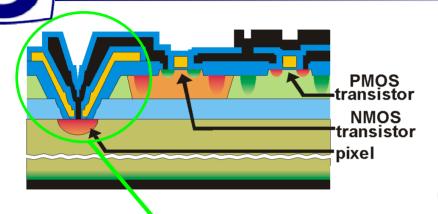
- Principle of the SOI sensor
- Advantages of the SOI monolithic active pixel sensor
- Preliminary measurements of the SOI sensors test structures sensor response calibration and linearity measurements
- SOI detector measurements with SUCIMA Imager DAQ system
- Design of the full size SOI sensor layout and readout scheme
- Alternative solutions of the SOI detector readout channel configurations

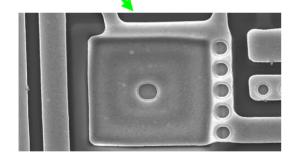
The SOI project is partially supported by the G1RD-CT-2001-000561

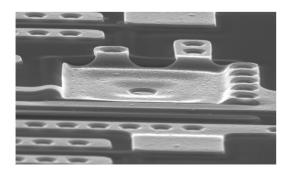




## Principle of SOI monolithic detector







### The idea:

Integration of the pixel detector and readout electronics in the wafer-bonded SOI substrate

#### Detector → handle wafer

- High resistive(> 4 kΩcm,FZ)
- 300 μm thick
- Conventional p+-n
- DC-coupled

### Electronics → active layer

- Low resistive (9-13 Ωcm, CZ)
- 1.5 μm thick
- Standard CMOS technology



## Advantages of the SOI detectors

## The SOI sensor may merge the advantages of the monolithic and hybrid detectors

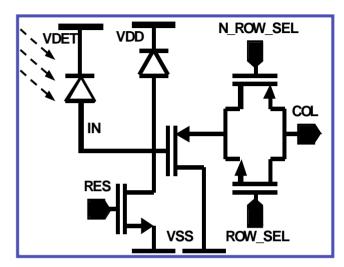
- As a monolithic device eliminates bump-bonding process and allows reduction of total sensor thickness → reduction of multiple scattering
- ➤ Allows using high resistive detector substrates and operation in fully depleted region → good detection efficiency, enables detection of particles with limited range in the silicon without backthinning process
- ➤ Gives possibility to use both type of transistors in readout channels → increased flexibility of the design, design optimisation for different application
- Tolerance of readout electronics for SEE benefits from reduction of active silicon thickness

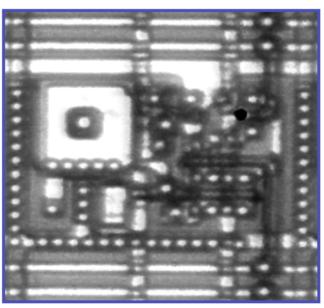
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## Test structures of the SOI detector

- Small readout matrices (8x8) with associated detector diodes were fabricated on the SOI wafers at the IET, Warsaw
- Optimised for medical imaging applications and high particle fluxes
- No digital control blocks
- Basic readout channel configuration similar to 3T cell, two variants:
  - with NMOS transistor switch
    - $\rightarrow$  cell dimensions 140x122  $\mu$ m<sup>2</sup>
    - → Measured dynamic range up to 150 MIP
  - with transmission gate
    - $\rightarrow$  cell dimensions 140x140  $\mu$ m<sup>2</sup>
    - → Measured dynamic range up to 300 MIP





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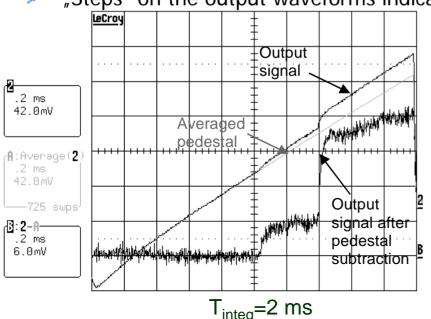


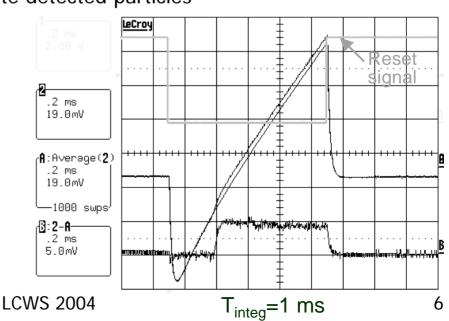
## Preliminary measurements of the SOI sensor test matrices

- Matrices with one-transistor switches were chosen for the preliminary tests of the sensor. Matrix dimensions: 1120 μm 976 μm.
- Detector leakage currents from 400 nA/cm² down to 10 nA/cm² depending on the process were achieved.
- Detector full depletion voltage of Vdet = 60 V down to 50 V for different iterations were measured.
- Detector sensitivity for ionising radiation have been tested with infrared laser light and alpha and beta particle sources

#### Strontium 90 beta source – recorded events in the detector

"Steps" on the output waveforms indicate detected particles



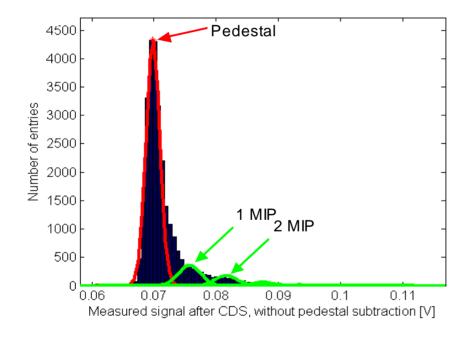


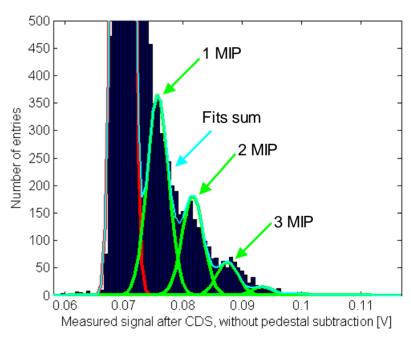


## Calibration of the SOI sensor

- Radioactive source: Sr90 beta source
- > Integration time:  $T_{int} = 500 \mu s$
- Detector polarization: V<sub>det</sub>= 60 V







Pedestal value =69.9 mV; pedestal width =  $2\cdot1.1$  mV First signal peak= 75.8 mV; signal peak width =  $2\cdot1.8$  mV

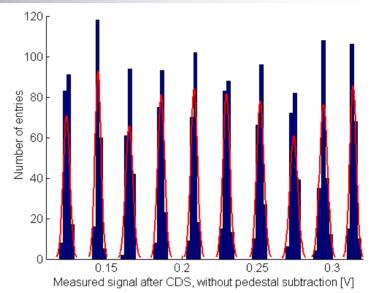
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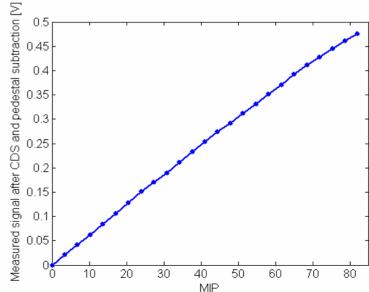


## Preliminary tests with the laser light

- Laser light not focused, shining from the backplane (biased by metal mash)
- Wavelength = 850 nm
- 4 μs wide light pulses each corresponding to 3.4 MIP
- Integration time = 1 ms
- Detector polarization=60V
- 10 000 events recorded

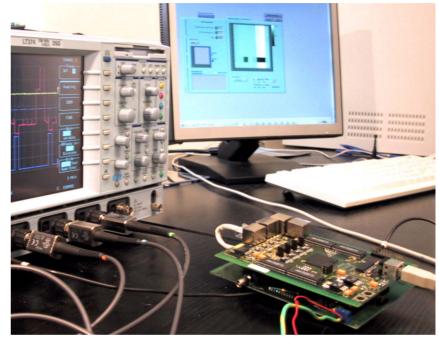
Good detector sensitivity for the ionising radiation and linear response as a function of the generated charge was observed.

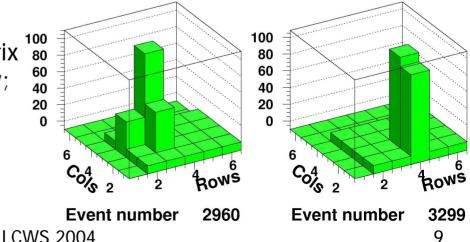




## SUCIMA Imager DAQ for the SOI detector

- Further measurements of the SOI detector test structures were performed with DAQ system called "SUCIMA Imager" developed at INP Krakow\* for the SUCIMA project
- The DAQ is equipped with 4 independent analogue input channels with 12 bit ADCs and a 1MB fast Static RAMs, the FPGA Virtex II XC2V1000 chip for advanced algorithms and the high speed USB 2.0 port for a fast data transfer to and from a PC computer.
- GUI developed in LabVIEW environment, allows setting: the matrix size to be readout, readout frequency; it provides: the CDS or Last Frame readout mode, masking noisy pixels, subtracting pedestals, suppressing signals bellow threshold and writing data to the file.

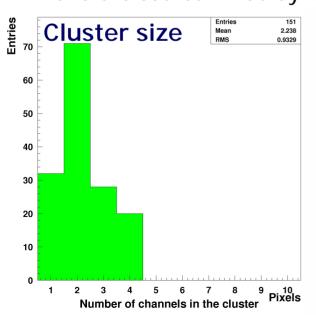


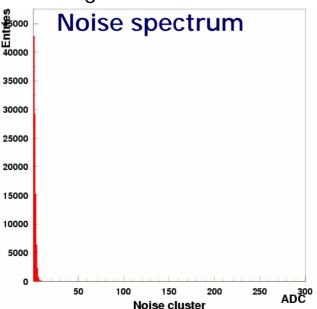


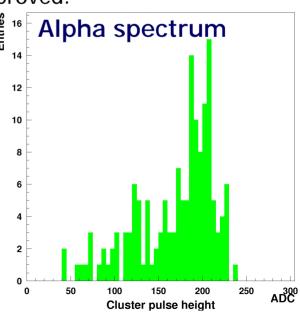


## Measurements of alpha particles spectrum

- Alpha source placed at the distance of 1 cm from the detector backplane, detector fully depleted (V<sub>D</sub>=70 V), integration time 720 μs
- On-line CDS processing, off-line pedestal subtraction, common mode suppression and cluster search
- Initial energy of particles = 5.5 MeV
- Typical measured cluster pulse height ≈ 200 ADC corresponding to about half of the alpha particles initial energy (roughly 25 MIPs)
- > Pedestal width about 1.5 ADC, S/N for typical cluster pulse height ≈130
- Broad spectrum due to the air presence and the large distance between the detector and the source. Wide dynamic range of the detector was proved.



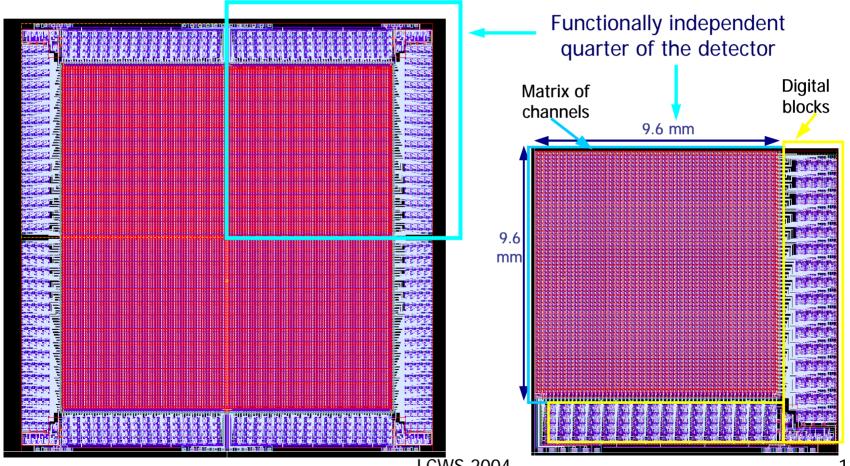






## From test structures to the fully functional sensor...

- Optimised for medical imaging applications and high particle flux
- $\rightarrow$  Dimensions: 24x24 mm<sup>2</sup>, 128 x 128 = 16 384 channels
- 4 sub-segments with independent parallel analogue outputs



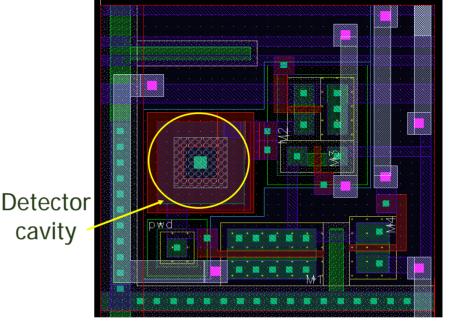


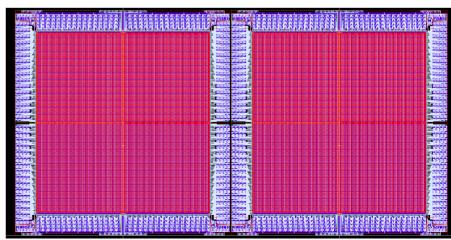
## Design of a fully functional SOI sensor

- Cell dimensions: 150x150µm²
- Cell configurations like on the test structures
- Construction of pixel connection like on the test structures
- Signal per MIP: ~ 6 mV
- Dynamic range: 300 MIP
- The basic detectors may be extended to the ladders, but with dead areas

The design is completed.

The chips are expected to be produced in July 2004

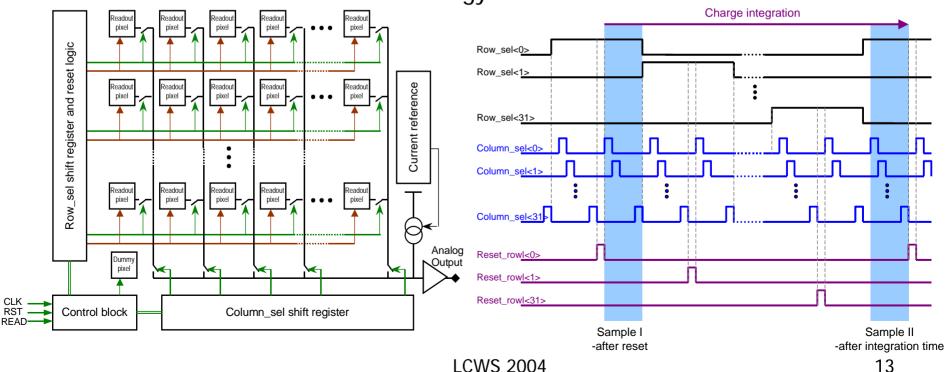






## Implemented SOI sensor readout

- Operation in un-triggered mode (for imaging applications)
- Analogue serial readout organisation
- Readout sequence similar to rolling-shutter but double sampling performed for every row
- External subtraction of samples for CDS
- Well defined integration time and short dead time
- Exercised and validated on the prototype chip designed in commercial AMS 0.8 technology

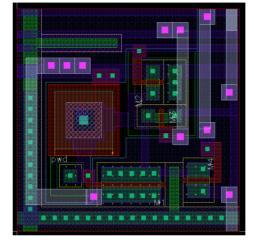


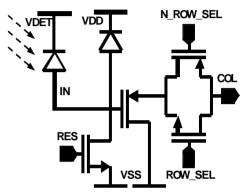


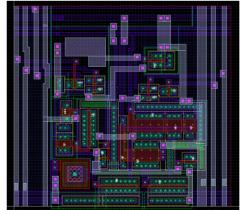
## Alternative solutions of the SOI detector cell

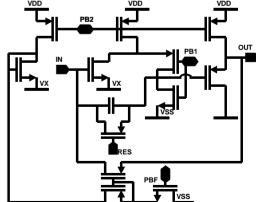
For the purpose of applications were lower signals levels expected alternative solutions of sensor cells proposed:

- Cell configuration similar like on the main detector but new construction of the contact to the pixel
  - Input capacitance reduced by factor of ~ 2
  - Signal per MIP ~ 12 mV
  - Dynamic range of 150 MIP
  - Test matrix of 16 x 16 cells
- Traditional charge sensitive amplifier
  - Signal per MIP ~ 160 mV
  - Better noise performance
  - No input protection diode required
  - Global reset and sample & hold
  - Test matrix of 16 x 8 cells
  - Detector contacts both standard and with reduced input capacitance









## Summary

- An alternative solution of a monolithic active pixel detector, which allows efficient detection in high resistive substrate, has been proposed.
- First small area SOI pixel sensors have been fabricated.
- Preliminary tests with a laser light and radioactive sources have indicated detector sensitivity for the ionising radiation and wide dynamic range. Detailed tests are carried-on.
- The SOI sensor with the active area of 2 cm x 2 cm, optimised for medical imaging applications and high particle fluxes has been designed and will be fabricated this summer.
- Alternative solutions of sensor cells dedicated for low particle fluxes have been proposed.